

**AMENDMENTS TO THE CLAIMS**

1-18. (Cancelled).

19. (Currently Amended) A suspension comprising:

a suspension bonding pad for electrically bonding a magnetic head terminal, wherein said bonding pad includes a metal pad having a bonding substance applied as a surface finishing material, the surface finishing material being heat treated prior to bonding to a surface; and

a slider bonding pad initially without bonding substance coupled to said suspension such that the bonding substance on said suspension bonding pad is reflowed so as to electrically couple the suspension bonding pad and the slider bonding pad, wherein the slider bonding pad enables the reuse of the suspension by removing the connection between a slider and the slider bonding pad with heat treatment, and further wherein a plurality of traces extend longitudinally ~~along the~~ generally along the center of a suspension~~[[the]]~~ and extend ~~around~~ along the ~~outer lateral~~ edges of a slider to ~~[[the]]~~ a trailing edge of the slider, ~~and electrically couple the slider to the suspension.~~

20. (Previously Presented) The suspension as claimed in claim 19, wherein said bonding substance is solder.

21. (Previously Presented) The suspension as claimed in claim 19, wherein said bonding substance is a conductive polymer.



Application No.: 09/741,684  
Amendment dated: December 3, 2008  
Reply to Office Action of September 3, 2008

22. (Previously Presented) The suspension as claimed in claim 19, wherein said bonding substance is an adhesive.

23. (Previously Presented) The suspension as claimed in claim 19, wherein said bonding substance is a film.

24. (Previously Presented) The suspension as claimed in claim 20, wherein a bump height for the solder is approximately 50-300  $\mu\text{m}$ , and a bump diameter for the solder is less than 180  $\mu\text{m}$ .

25-30. (Cancelled).